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ON Semiconductor MMBT2907AM3T5G

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## MMBT2907AM3T5G

## **PNP General Purpose** Transistor

The MMBT2907AM3T5G device is a spin-off of our popular SOT-23 three-leaded device. It is designed for general purpose amplifier applications and is housed in the SOT-723 surface mount package. This device is ideal for low-power surface mount applications where board space is at a premium.

### Features

- Reduces Board Space
- This is a Halide–Free Device
- This is a Pb–Free Device

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V <sub>CEO</sub>	-60	Vdc
Collector – Base Voltage	V <sub>CBO</sub>	-60	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	-5.0	Vdc
Collector Current – Continuous	Ι <sub>C</sub>	-600	mAdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Мах	Unit
Total Device Dissipation FR-5 Board (Note 1) T <sub>A</sub> = 25°C Derate above 25°C	PD	265 2.1	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	470	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	640 5.1	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	195	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	–55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

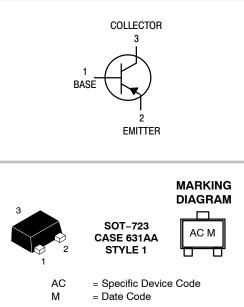
1. FR-5 = 1.0  $\times$  0.75  $\times$  0.062 in.

2. Alumina = 0.4  $\times$  0.3  $\times$  0.024 in. 99.5% alumina.



## **ON Semiconductor®**

http://onsemi.com



#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMBT2907AM3T5G	SOT-723 (Pb-Free)	

+ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



## MMBT2907AM3T5G

## **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = $25^{\circ}$ C unless otherwise noted)

Characteristic			Min	Max	Unit
OFF CHARACTERISTICS					
Collector-Emitter Breakdown Voltage (Note 3) $(I_{\rm C} = -10 \text{ mAdc}, I_{\rm B} = 0)$		V <sub>(BR)CEO</sub>	-60	-	Vdc
Collector – Base Breakdown Voltage ( $I_C = -10 \ \mu Adc, I_E = 0$ )		V <sub>(BR)CBO</sub>	-60	-	Vdc
Emitter – Base Breakdown Voltage ( $I_E = -10 \ \mu Adc, I_C = 0$ )		V <sub>(BR)EBO</sub>	-5.0	-	Vdc
Collector Cutoff Current ( $V_{CE} = -30$ Vdc, $V_{EB(off)} = -0.5$ Vdc)		I <sub>CEX</sub>	-	-50	nAdc
Collector Cutoff Current ( $V_{CB} = -50$ Vdc, $I_E = 0$ ) ( $V_{CB} = -50$ Vdc, $I_E = 0$ , $T_A = 125^{\circ}C$ )		I <sub>CBO</sub>		-0.010 -10	μAdc
Base Cutoff Current (V <sub>CE</sub> = –30 Vdc, V <sub>EB(off)</sub> = –0.5 Vdc)		I <sub>BL</sub>	-	-50	nAdc
ON CHARACTERISTICS		•			
$ \begin{array}{l} \text{DC Current Gain} \\ (I_{C} = -0.1 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}) \\ (I_{C} = -1.0 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}) \\ (I_{C} = -10 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}) \\ (I_{C} = -150 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}) \\ (I_{C} = -500 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}) \\ (I_{C} = -500 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}) \\ (\text{Note 3}) \end{array} $		h <sub>FE</sub>	75 100 100 100 50	- - 300 -	-
$      Collector - Emitter Saturation Voltage (Note 3) \\       (I_C = -150 mAdc, I_B = -15 mAdc) (Note 3) \\        (I_C = -500 mAdc, I_B = -50 mAdc) $		V <sub>CE(sat)</sub>	-	-0.4 -1.6	Vdc
Base – Emitter Saturation Voltage (Note 3) ( $I_C = -150$ mAdc, $I_B = -15$ mAdc) ( $I_C = -500$ mAdc, $I_B = -50$ mAdc)		V <sub>BE(sat)</sub>		-1.3 -2.6	Vdc
SMALL-SIGNAL CHARACTERISTICS					
Current-Gain - Bandwidth Product (Notes 3, 4) $(I_C = -50 \text{ mAdc}, V_{CE} = -20 \text{ Vdc}, f = 100 \text{ MHz})$		fT	200	-	MHz
Output Capacitance $(V_{CB} = -10 \text{ Vdc}, I_E = 0, f = 1.0 \text{ MHz})$		C <sub>obo</sub>	-	8.0	pF
Input Capacitance (V <sub>EB</sub> = -2.0 Vdc, I <sub>C</sub> = 0, f = 1.0 MHz)		C <sub>ibo</sub>	-	30	
SWITCHING CHARACTERISTICS					
Turn-On Time		t <sub>on</sub>	-	45	
Delay Time	(V <sub>CC</sub> = –30 Vdc, I <sub>C</sub> = –150 mAdc, I <sub>B1</sub> = –15 mAdc)	t <sub>d</sub>	-	10	
Rise Time		tr	-	40	

		۲r	-	40	
Turn–Off Time		t <sub>off</sub>	-	100	ns
Storage Time	(V <sub>CC</sub> = −6.0 Vdc, I <sub>C</sub> = −150 mAdc, I <sub>B1</sub> = I <sub>B2</sub> = −15 mAdc)	t <sub>s</sub>	-	80	
Fall Time		t <sub>f</sub>	-	30	

3. Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2.0%.

4.  $f_{T}$  is defined as the frequency at which  $\left|h_{fe}\right|$  extrapolates to unity.



## MMBT2907AM3T5G

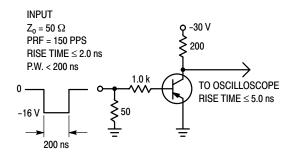


Figure 1. Delay and Rise Time Test Circuit

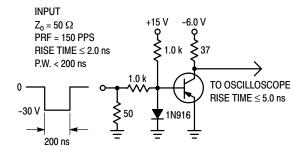
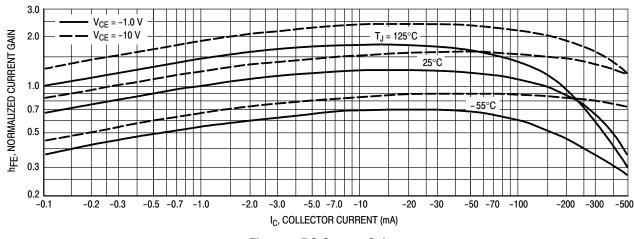


Figure 2. Storage and Fall Time Test Circuit

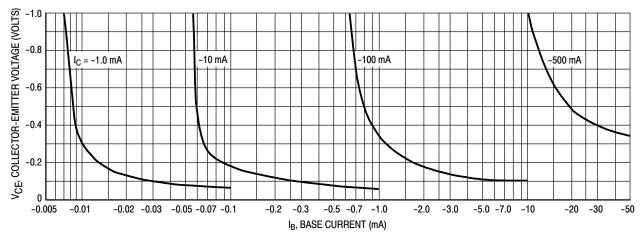


## MMBT2907AM3T5G

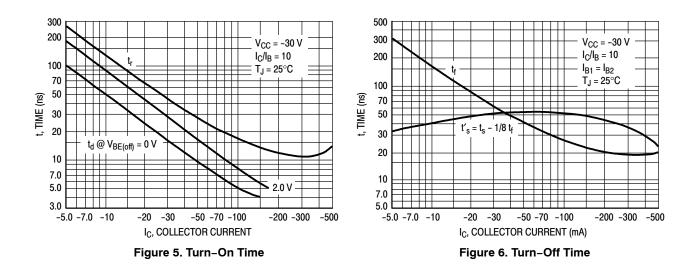
**TYPICAL CHARACTERISTICS** 











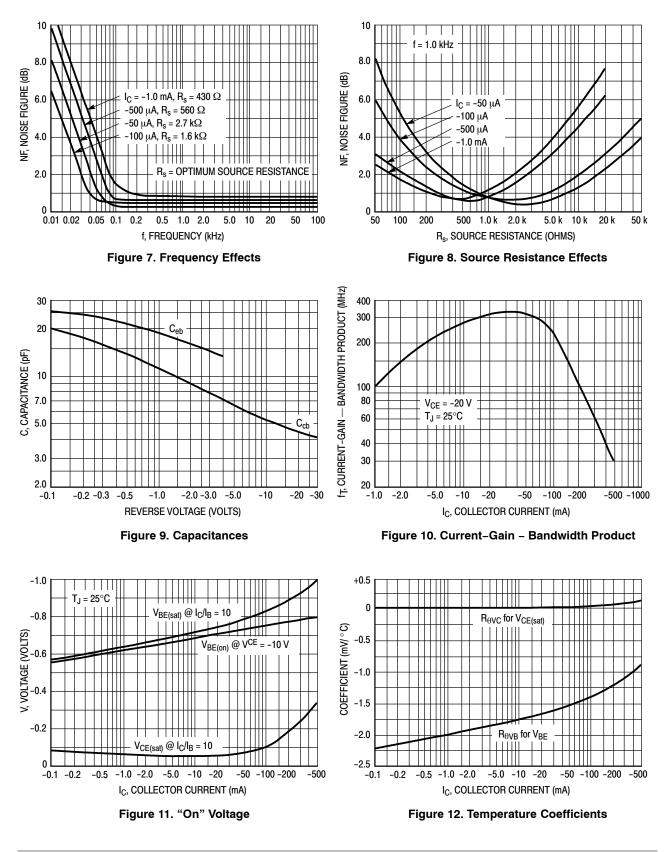


## MMBT2907AM3T5G



NOISE FIGURE

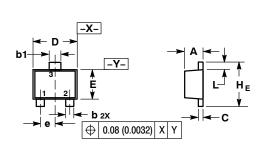
 $V_{CE}$  = 10 Vdc,  $T_A$  = 25°C





## MMBT2907AM3T5G

#### PACKAGE DIMENSIONS



SOT-723 CASE 631AA-01 **ISSUE C** 

NOTES

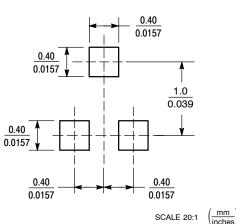
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETERS.
- CONTROLLING DIMENSION: MILLIMETERS.
  MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD

FLASH, PROTRUSIONS OR GATE BURRS.
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	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.45	0.50	0.55	0.018	0.020	0.022	
b	0.15	0.21	0.27	0.0059	0.0083	0.0106	
b1	0.25	0.31	0.37	0.010	0.012	0.015	
С	0.07	0.12	0.17	0.0028	0.0047	0.0067	
D	1.15	1.20	1.25	0.045	0.047	0.049	
E	0.75	0.80	0.85	0.03	0.032	0.034	
е	0.40 BSC			C	.016 BS	С	
ΗE	1.15	1.20	1.25	0.045	0.047	0.049	
L	0.15	0.20	0.25	0.0059	0.0079	0.0098	

STYLE 1: PIN 1. BASE 2. EMITTER 3. COLLECTOR

#### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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